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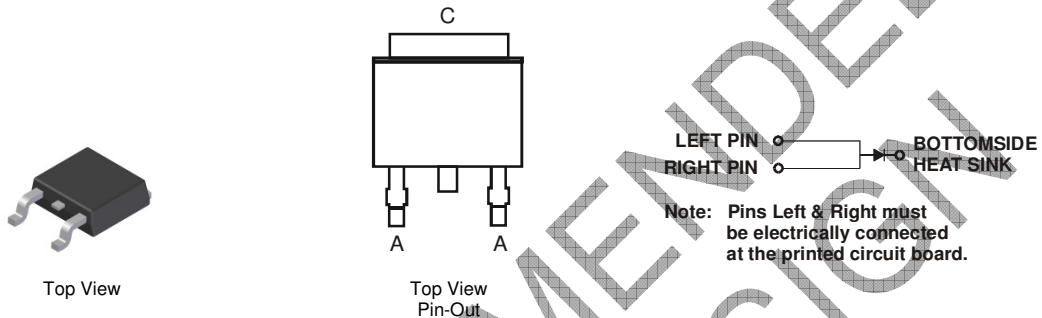


Features

- Ultra-Fast Die Construction
- Soft, Fast Switching Capability
- Low Leakage Current
- **Lead Free Finish, RoHS Compliant (Note 1)**
- **"Green" Molding Compound (No Br, Sb)**

Mechanical Data

- Case: TO252
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 ③
- Polarity: See Diagram

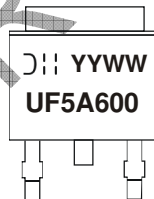


Ordering Information (Note 2)

Part Number	Case	Packaging
UF5A600D1-13	TO252	2500 pieces/reel

- Notes:
1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes.
 2. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



UF5A600 = Product Type Marking Code
 ⎓⎓⎓ = Manufacturers' Code Marking
 YYWW = Date code marking
 YY = Last two digits of year (ex: 09 for 2009)
 WW = Week code (01 - 53)

Maximum Ratings @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V_{RRM}	600	V
Working Peak Reverse Voltage	V_{RWM}		
DC Blocking Voltage	V_R		
Average Rectified Output Current	I_O	5	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I_{FSM}	100	A

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Case	$R_{\theta JC}$	2.0	$^\circ\text{C/W}$
Typical Thermal Resistance Junction to Ambient (Note 3)	$R_{\theta JA}$	34	$^\circ\text{C/W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +175	$^\circ\text{C}$

Electrical Characteristics @ $T_A = 25^\circ\text{C}$ unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage	V_F	—	1.4	1.9	V	$I_F = 5\text{A}, T_J = 25^\circ\text{C}$ $I_F = 5\text{A}, T_J = 125^\circ\text{C}$
Reverse Leakage Current (Note 4)	I_R	—	—	10	μA	$V_R = 600\text{V}, T_J = 25^\circ\text{C}$
				0.2	mA	$V_R = 600\text{V}, T_J = 125^\circ\text{C}$
Reverse Recovery Time	t_{rr}	—	22	30	ns	$I_F = 0.5\text{A}, I_R = 1.0\text{A}, I_{rr} = 0.25\text{A}$ $I_F = 1\text{A}, V_R = 30\text{V}, di/dt = 100\text{A}/\mu\text{s}$
Maximum Junction Capacitance	C_J	—	27	50	pf	$V_R = 10\text{V}_{DC}, f = 1\text{MHz}$

Notes: 3. Device mounted on Polyimide PCB, with 16X recommended pad layout.
4. Short duration pulse test used to minimize self-heating effect.

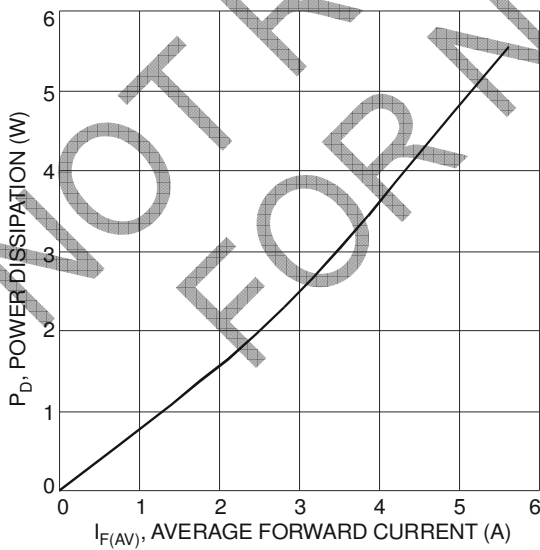


Fig. 1 Forward Power Dissipation

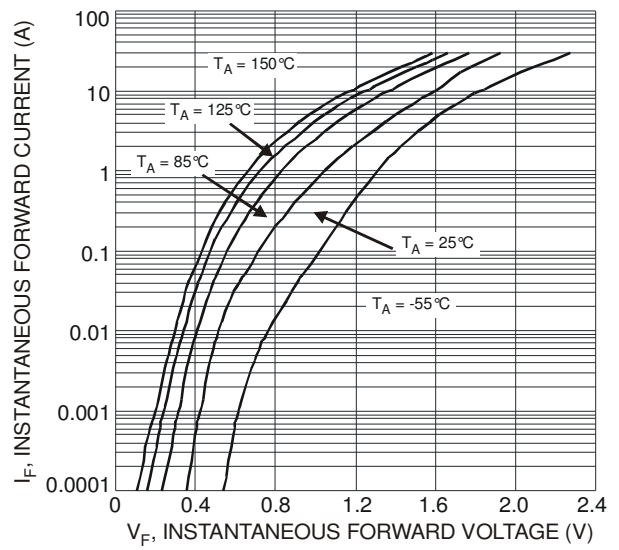


Fig. 2 Typical Forward Characteristics

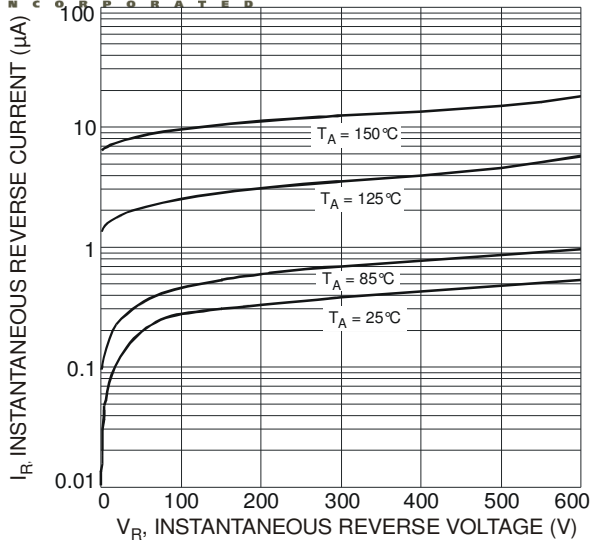


Fig. 3 Typical Reverse Characteristics

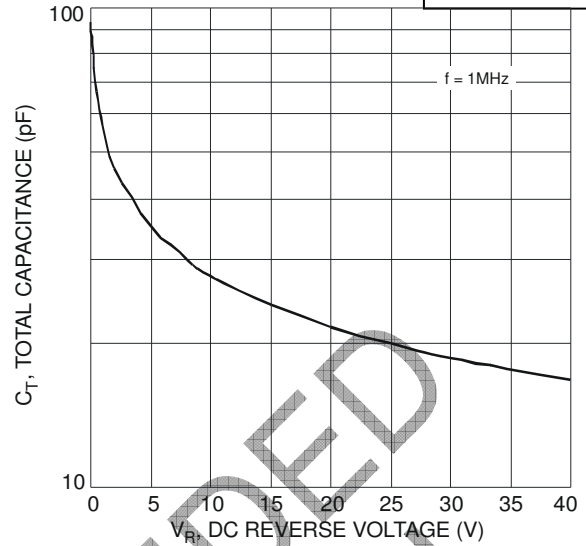


Fig. 4 Total Capacitance vs. Reverse Voltage

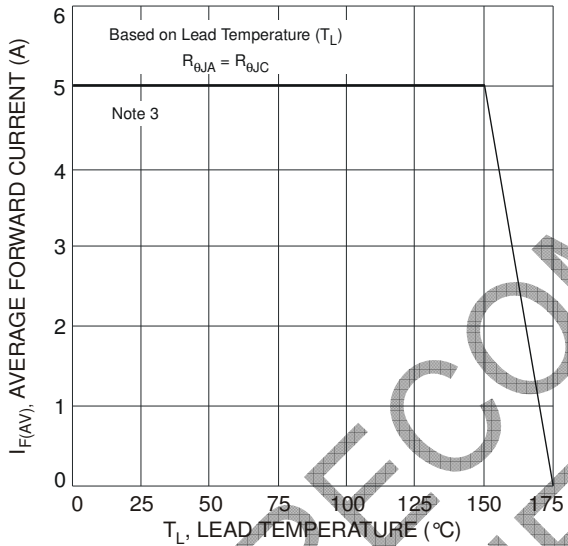


Fig. 5 Forward Current Derating Curve

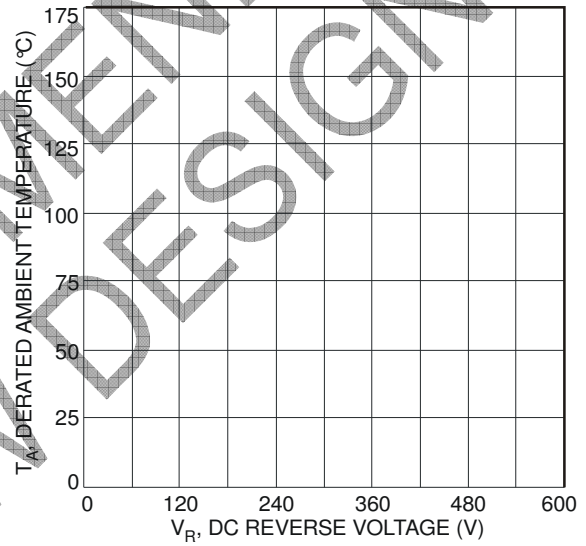
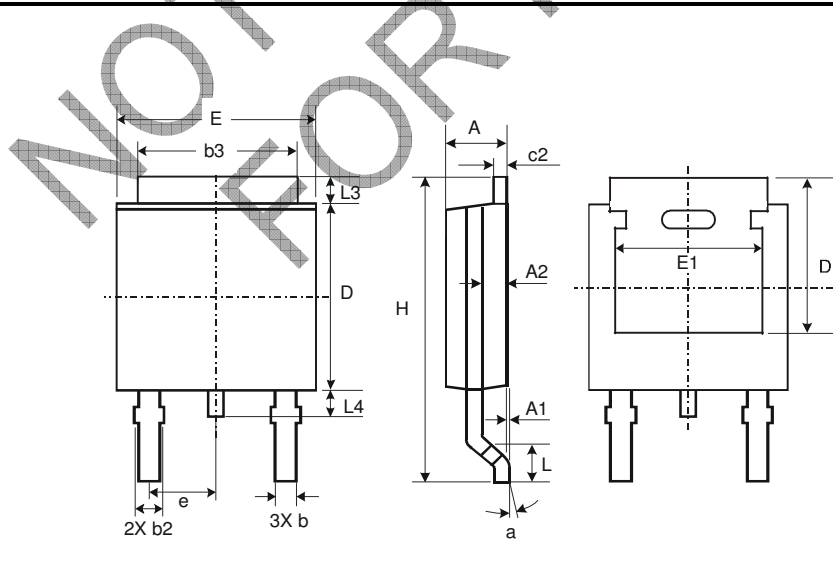


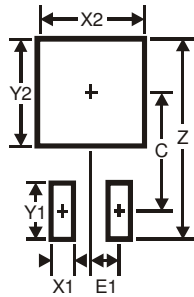
Fig. 6 Operating Temperature Derating

Package Outline Dimensions



TO252			
Dim	Min	Max	Typ
A	2.19	2.39	2.29
A1	0.00	0.13	0.08
A2	0.97	1.17	1.07
b	0.64	0.88	0.783
b2	0.76	1.14	0.95
b3	5.21	5.46	5.33
c2	0.45	0.58	0.531
D	6.00	6.20	6.10
D1	5.21	-	-
e	-	-	2.286
E	6.45	6.70	6.58
E1	4.32	-	-
H	9.40	10.41	9.91
L	1.40	1.78	1.59
L3	0.88	1.27	1.08
L4	0.64	1.02	0.83
a	0°	10°	-
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
Z	11.6
X1	1.5
X2	7.0
Y1	2.5
Y2	7.0
C	6.9
E1	2.3

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